

SVENSK STANDARD

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Bestämning av effekttäthet avseende exponering för radiofrekventa fält från trådlösa enheter i närheten av huvud och kropp (frekvensområde 6 GHz till 300 GHz) – Del 1: Mätmetod

Assessment of power density of human exposure to radio frequency fields from wireless devices in close proximity to the head and body (frequency range of 6 GHz to 300 GHz) – Part 1: Measurement procedure

Som svensk standard gäller europastandarden EN IEC/IEEE 63195-1:2023. Den svenska standarden innehåller den officiella engelska språkversionen av EN IEC/IEEE 63195-1:2023.

Nationellt förord

Europastandarden EN IEC/IEEE 63195-1:2023

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utarbetad inom International Electrotechnical Commission, IEC.

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Assessment of power density of human exposure to radio frequency fields from wireless devices in close proximity to the head and body (frequency range of 6 GHz to 300 GHz) - Part 1: Measurement procedure (IEC/IEEE 63195-1:2022)

Évaluation de la densité de puissance de l'exposition humaine aux champs radiofréquences provenant de dispositifs sans fil à proximité immédiate de la tête et du corps (plage de fréquences de 6 GHz à 300 GHz) -Partie 1: Procédure de mesure (IEC/IEEE 63195-1:2022) Bewertung der Leistungsdichte der Exposition des Menschen gegenüber hochfrequenten Feldern von drahtlosen Geräten in unmittelbarer Nähe des Kopfes und des Körpers (Frequenzbereich von 6 GHz bis 300 GHz) -Teil 1: Messverfahren (IEC/IEEE 63195-1:2022)

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European foreword

This document (EN IEC/IEEE 63195-1:2023) consists of the text of document IEC/IEEE 63195-1:2022, prepared by IEC/TC 106 "Methods for the assessment of electric, magnetic and electromagnetic fields associated with human exposure".

The following dates are fixed:

| • | latest date by which this document has to be (dop) | 2024-01-09 |
|---|--|------------|
| | implemented at national level by publication of an | |
| | identical national standard or by endorsement | |

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In the official version, for Bibliography, the following notes have to be added for the standard indicated:

| ISO/IEC 17025:2017 | NOTE | Harmonized as | EN ISO/IEC | 17025:2017 | (not modified) |
|--------------------|------|---------------|------------|------------|----------------|
| | | | | | (|

IEC 62311:2019 NOTE Harmonized as EN IEC 62311:2020 (not modified)

ISO/IEC 17043:2010 NOTE Harmonized as EN ISO/IEC 17043:2010 (not modified)

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: <u>www.cenelec.eu</u>.

| Publication | Year | <u>Title</u> | | | | <u>EN/HD</u> | Year |
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Évaluation de la densité de puissance de l'exposition humaine aux champs radiofréquences provenant de dispositifs sans fil à proximité immédiate de la tête et du corps (plage de fréquences de 6 GHz à 300 GHz) – Partie 1: Procédure de mesure

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

ASSESSMENT OF POWER DENSITY OF HUMAN EXPOSURE TO RADIO FREQUENCY FIELDS FROM WIRELESS DEVICES IN CLOSE PROXIMITY TO THE HEAD AND BODY (FREQUENCY RANGE OF 6 GHz TO 300 GHz) –

Part 1: Measurement procedure

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This document is published as an IEC/IEEE Dual Logo standard.

This publication contains supplemental files in the form of analytical reference functions for validation of the reconstruction algorithms in Annex E. Download links for these files can be found in Clause E.5.

The text of this International Standard is based on the following IEC documents:

| Draft | Report on voting |
|--------------|------------------|
| 106/565/FDIS | 106/570/RVD |

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with the rules given in the ISO/IEC Directives, Part 2, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC/IEEE 63195 series, published under the general title Assessment of power density of human exposure to radio frequency fields from wireless devices in close proximity to the head and body, can be found on the IEC website.

The IEC Technical Committee and IEEE Technical Committee have decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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INTRODUCTION

This document provides methods to evaluate incident power density exposures due to any electromagnetic field (EMF) transmitting device intended to be used at a position near the human head or body, or mounted on the body, combined with other transmitters within a product, or embedded in garments. The device categories covered include but are not limited to mobile telephones, radio transmitters in personal computers, and desktop and laptop devices. This document also addresses multi-band and multi-antenna devices. The overall applicable frequency range is from 6 GHz to 300 GHz. This document specifies:

- measurement system (Clause 6);
- power density measurement protocols (Clause 7);
- uncertainty evaluation (Clause 8);
- measurement report (Clause 9);
- system checks and system validation (Annex B).

To develop this document, IEC Technical Committee 106 (TC 106) and Technical Committee 34 (TC 34) Subcommittee 1 (SC 1) of IEEE International Committee on Electromagnetic Safety (ICES) formed Joint Working Group 12 (JWG 12) on measurement methods to assess the power density of electromagnetic fields from wireless devices in close proximity to the head and body.

This document is partly based on IEC TR 63170:2018.

NOTE System validation tests are specified in Annex B for 10 GHz, 30 GHz, 60 GHz, and 90 GHz to cover the frequency range from 6 GHz to 110 GHz. Additional validation antennas to cover the frequency range up to 300 GHz will be developed in a future revision of this document. Further discussion on rationales is given in Annex I.

ASSESSMENT OF POWER DENSITY OF HUMAN EXPOSURE TO RADIO FREQUENCY FIELDS FROM WIRELESS DEVICES IN CLOSE PROXIMITY TO THE HEAD AND BODY (FREQUENCY RANGE OF 6 GHz TO 300 GHz) –

Part 1: Measurement procedure

1 Scope

This document specifies protocols and test procedures for repeatable and reproducible measurements of power density (PD) that provide conservative estimates of exposure incident to a human head or body due to radio-frequency (RF) electromagnetic field (EMF) transmitting communication devices, with a specified measurement uncertainty. These protocols and procedures apply for exposure evaluations of a significant majority of the population during the use of hand-held and body-worn RF transmitting communication devices. The methods apply for devices that can feature single or multiple transmitters or antennas, and can be operated with their radiating structure(s) at distances up to 200 mm from a human head or body.

The methods of this document can be used to determine conformity with applicable maximum PD requirements of different types of RF transmitting communication devices being used in close proximity to the head and body, including if combined with other RF transmitting or non-transmitting devices or accessories (e.g. belt-clip), or embedded in garments. The overall applicable frequency range of these protocols and procedures is from 6 GHz to 300 GHz.

The RF transmitting communication device categories covered in this document include but are not limited to mobile telephones, radio transmitters in personal computers, desktop and laptop devices, and multi-band and multi-antenna devices.

NOTE 1 System validation tests are specified in Annex B for 10 GHz, 30 GHz, 60 GHz, and 90 GHz to cover the frequency range from 6 GHz to 110 GHz. Additional validation antennas to cover the frequency range up to 300 GHz will be developed in a future revision of this document. Further discussion on rationales is given in Annex I.

NOTE 2 The protocols and test procedures in this document can be adapted to evaluate exposure also due to noncommunication types of devices operating in close proximity to the head and body, but these devices are not in the scope of this document.

NOTE 3 For the assessment of the combined exposure from simultaneous transmitters operating on frequencies below 6 GHz, the relevant standards for SAR measurements are IEC/IEEE 62209-1528:2020 and IEC/IEEE 62209-3:2019 [1].

NOTE 4 Between 6 GHz and 10 GHz, the scopes of this document and IEC/IEEE 62209-1528:2020 overlap. According to ICNIRP [2] guidelines and IEEE ICES C95.1 [3] standard, power density is the conformity metric in this frequency range. SAR can be used as conformity metric if local regulatory requirements allow it. (e.g. in case where a single transmit band includes test channels at both below and above 6 GHz).

The procedures of this document do not apply for EMF measurements of devices or objects intended to be implanted in the body.

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2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC/IEEE 62209-1528:2020, Measurement procedure for the assessment of specific absorption rate of human exposure to radio frequency fields from hand-held and body-mounted wireless communication devices – Part 1528: Human models, instrumentation, and procedures (Frequency range of 4 MHz to 10 GHz)

IEC/IEEE 63195-2:2021¹, Assessment of power density of human exposure to radio frequency fields from wireless devices in close proximity to the head and body (Frequency range of 6 GHz to 300 GHz) – Part 2: Computational procedure

¹ To be published.